

描述 / Descriptions

肖特基整流二极管，薄型 SOD-323FL 封装。

Schottky Barrier Rectifiers,SOD-323FL thin package.

特征 / Features

低功耗，高效率，高电流，正向压降低，浪涌能力高，适用于低压，高频逆变器。无卤产品。

Low power loss, high efficiency . High current capability , low forward voltage drop , High surge capability, For use in low voltage, high frequency inverters .Halogen free product.

用途 / Applications

一般用途。 .

General purpose.

内部等效电路 / Equivalent Circuit

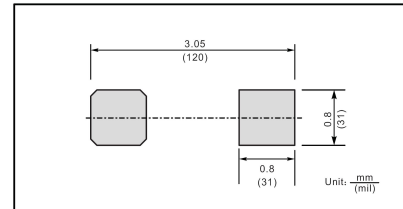


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。 See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating			单位 Unit
		B5817WSFL	B5818WSFL	B5819WSFL	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	30	40	V
Maximum RMS voltage	V_{RMS}	14	21	28	V
Maximum DC Blocking Voltage	V_{DC}	20	30	40	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1.0			A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed On Rated Load (JEDEC method)	I_{FSM}	25			A
Typical Junction Capacitance	C_i	110			pF
Storage and Operating Junction Temperature Range	T_j, T_{stg}	-55~+125			°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating			单位 Unit
			B5817WSFL	B5818WSFL	B5819WSFL	
Maximum Instantaneous Forward Voltage	V_F	$I_F=1.0A$	0.45	0.55	0.60	V
		$I_F=3.0A$	0.75	0.875	0.90	
Maximum Instantaneous Reverse Current at Rated DC Reverse Voltage	I_R	$T_a=25^\circ C$	1.0			mA
		$T_a=100^\circ C$	10			mA

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

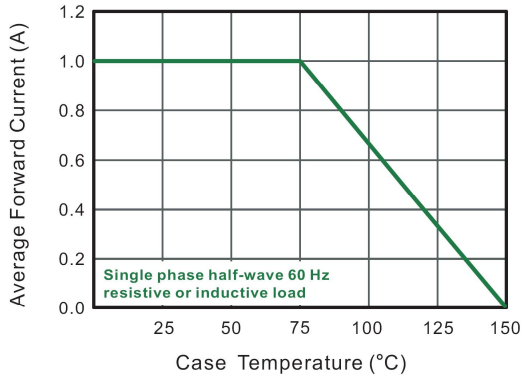


Fig.2 Typical Reverse Characteristics

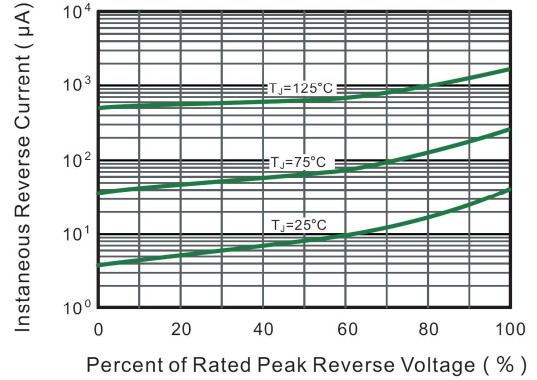


Fig.3 Typical Forward Characteristic

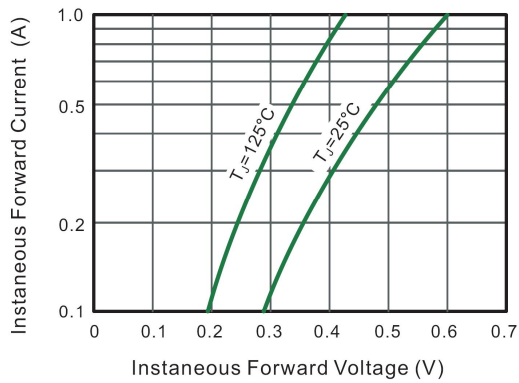


Fig.4 Typical Junction Capacitance

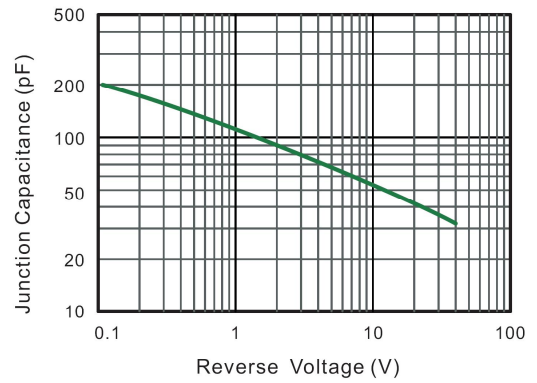
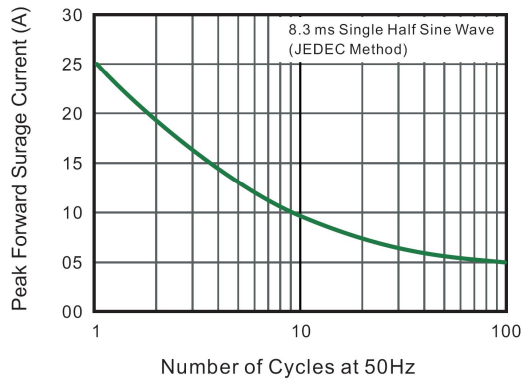


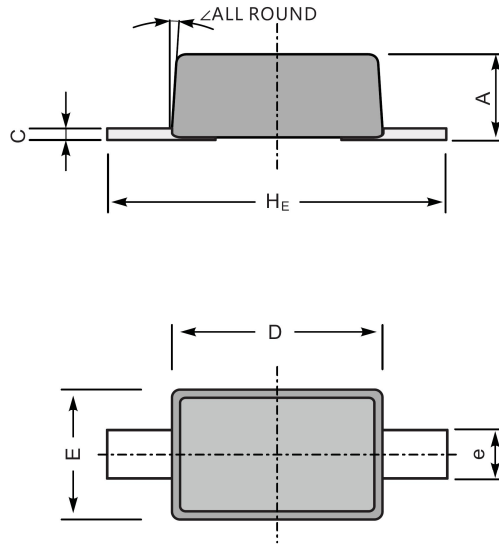
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



外形尺寸图 / Package Dimensions

Plastic surface mounted package; 2 leads

SOD-323FL

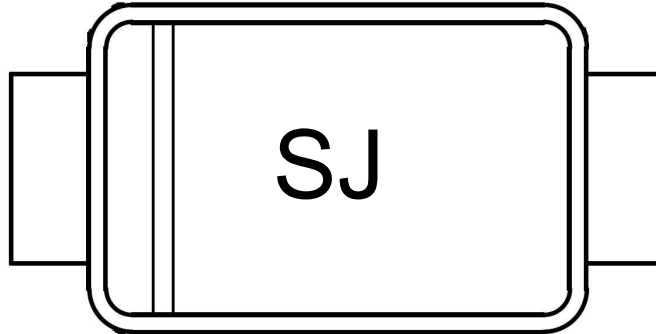


UNIT		A	C	D	E	e	H _E	z
mm	max	1.0	0.25	1.8	1.35	0.4	2.7	8°
	min	0.8	0.05	1.6	1.15	0.25	2.3	
mil	max	39	9.8	71	53	18	106	
	min	31	2.0	63	45	10	91	

Marking

Type number	Marking code
B5817WSFL	SJ
B5818WSFL	SK
B5819WSFL	SL

印章说明 / Marking Instructions



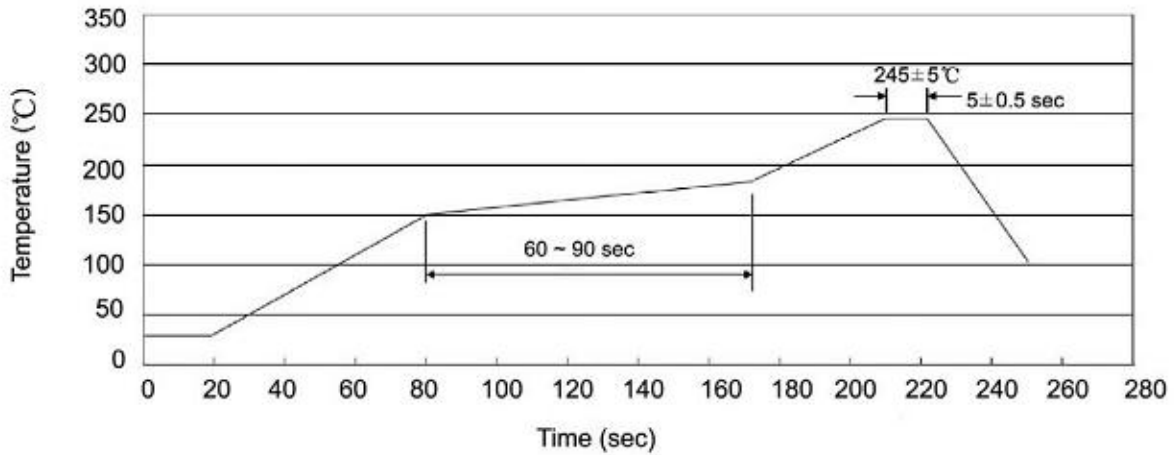
说明：

SJ：为型号代码

Note:

SJ：Product Type Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-323FL	3000	8	24000	6	144000	7" ×11	185X180X105	390X385X205

使用说明 / Notices